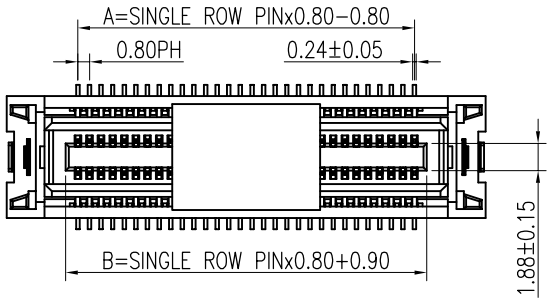
客户图

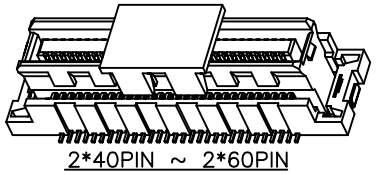
NOTES:

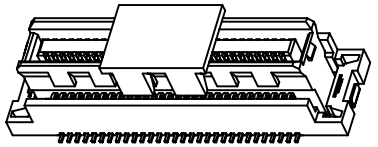
1. FINISH:
   - 1.1 HOUSING: LCP BLACK, UL94V-0.
   - 1.2 CONTACT: COPPER ALLOY,GOLD (SEE P/N) PLATED IN CONTACT AERA, GOLD FLASH PLATED IN SOLDER AREA, 50u" MIN. NICKEL UNDERPLATED OVERALL.
   - 1.3 GROUND: BRASS,80u" MIN. TIN PLATED OVER 50u" MIN. NICKEL UNDERPLATED OVERALL.
2. ELECTRICAL:
   - 2.1 CURRENT RATING: 0.5A;
   - 2.2 VOLTAGE RATING: 50V.
   - 2.3 CONTACT RESISTANCE: 120mΩ MAX.
   - 2.4 INSULATION RESISTANCE: 500MΩ MIN.
   - 2.5 OPERATION TEMPERATURE: -40°C TO +125°C.
3. ORDER INFORMATION:

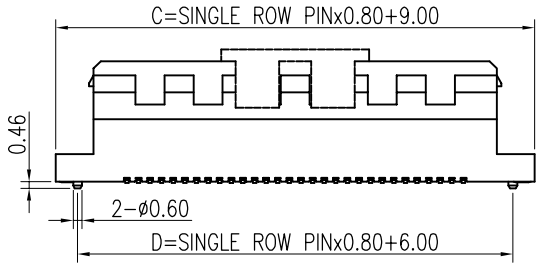
AA C8 F XXX XX XXX R 1

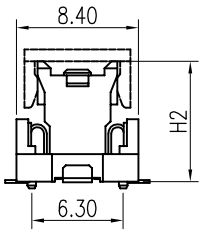
Pin数码	端子电镀：	塑胶高度：	包装方式：
010:2x05PIN	G0=Gold Flash	049=4.90mm	R=TAPE REEL
.....	G1=1u" Gold	083=8.30mm	
120:2x60PIN	G2=3u" Gold		
	G3=5u" Gold		
	G4=10u" Gold		
	G5=15u" Gold		
	G6=30u" Gold		











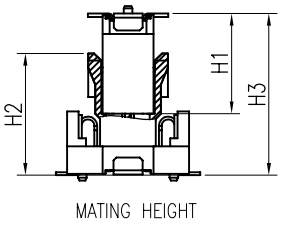
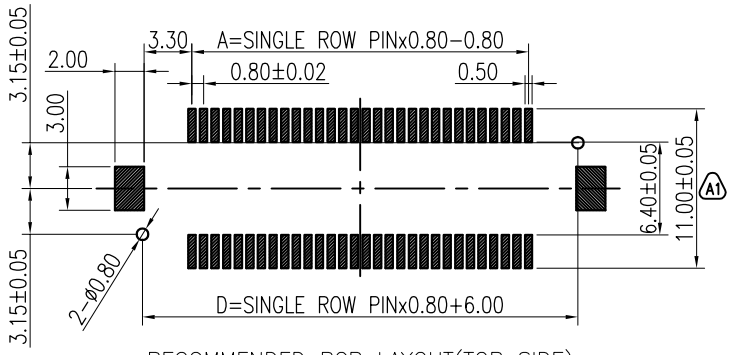


TABLE1:

No. OF PIN	A	B	C	D
010=2x05PIN	3.20	4.90	13.00	10.00
020=2x10PIN	7.20	8.90	17.00	14.00
030=2x15PIN	11.20	12.90	21.00	18.00
040=2x20PIN	15.20	16.90	24.00	22.00
050=2x25PIN	19.20	20.90	29.00	26.00
060=2x30PIN	23.20	24.90	33.00	30.00
080=2x40PIN	31.20	32.90	41.00	38.00
100=2x50PIN	39.20	40.90	49.00	46.00
120=2x60PIN	43.20	44.90	53.00	50.00



RECOMMENDED PCB LAYOUT(TOP SIDE)
PCB BOARD TOLFRANCF±0.05

MATING HEIGHT	H1	H2	H3
6.50mm	4.80	4.90	6.50
8.00mm	6.80		8.00
9.00mm	7.80		9.00
9.75mm	4.80	8.30	9.75
11.75mm	6.80		11.75
12.75mm	7.80		12.75

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE
A4	2022.08.02	柱子高度由0.60改回0.46	WLY	
A3	2022.06.10	柱子加高到0.6，80PIN以上增加台阶释放应力	WLY	
A2	2022.05.07	更新PCB LAYOUT	WLY	
A0		NEW	———	———

OPERATION	
X.X	±0.40
X.XX	±0.25
X.XXX	±0.15
Angle	±3°
DIM.	TOL

DRAW	WLY	2022.08.02
DESIGN	Jensen	2022.08.02
CHECK	Jack	2022.08.02
APPROVE	Andy	2022.08.02
UNIT	mm	SCALE 1:1

CONSHARE

SIZE	A4	PART NO.	AAC8FXXXXXXXXR1
SHEET	1/1	TITLE:	浮动BTB PH0.80mm 母座直立式SMT
PROJ.		DRAW NO.	366